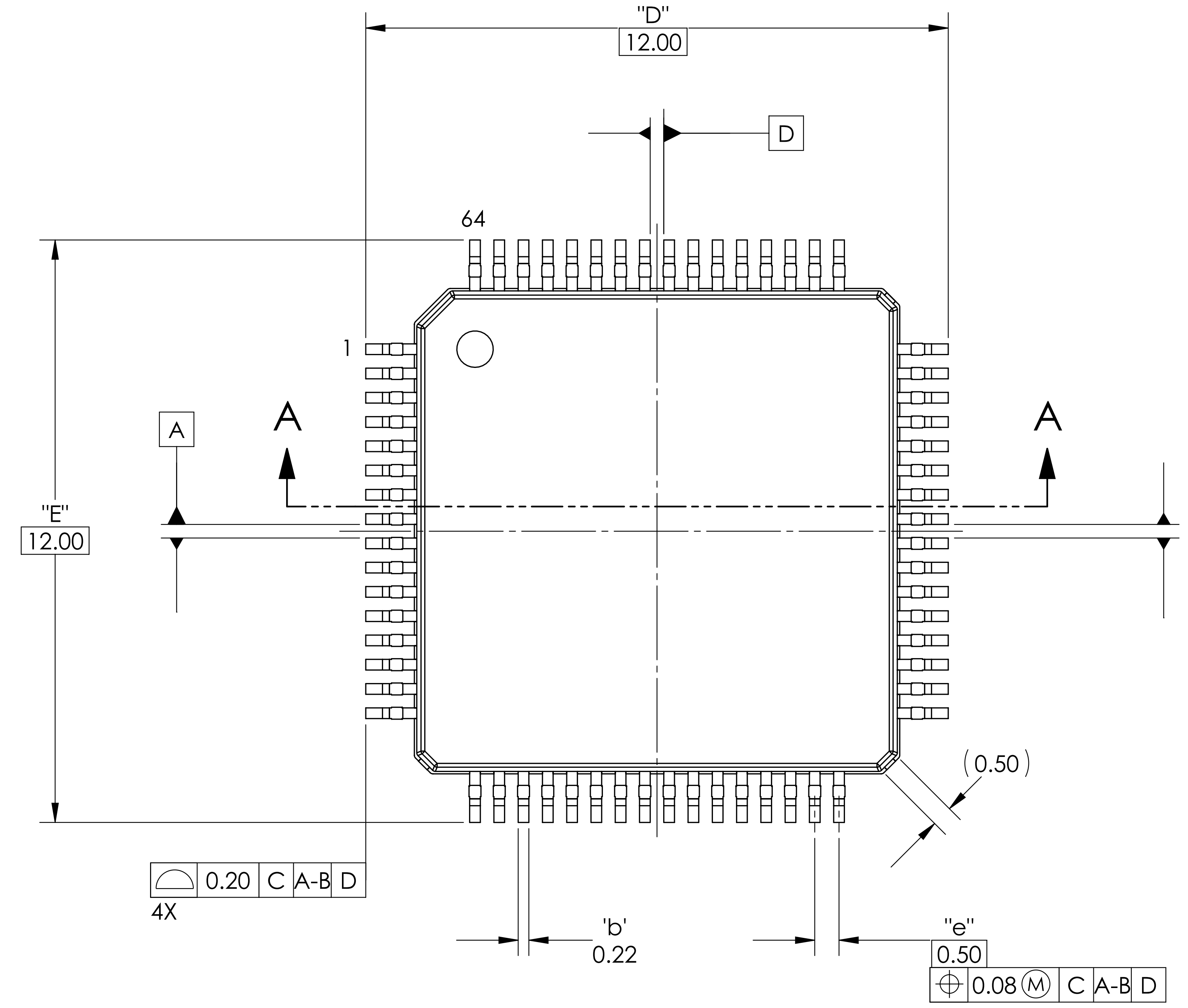
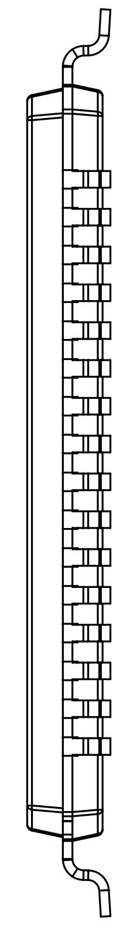
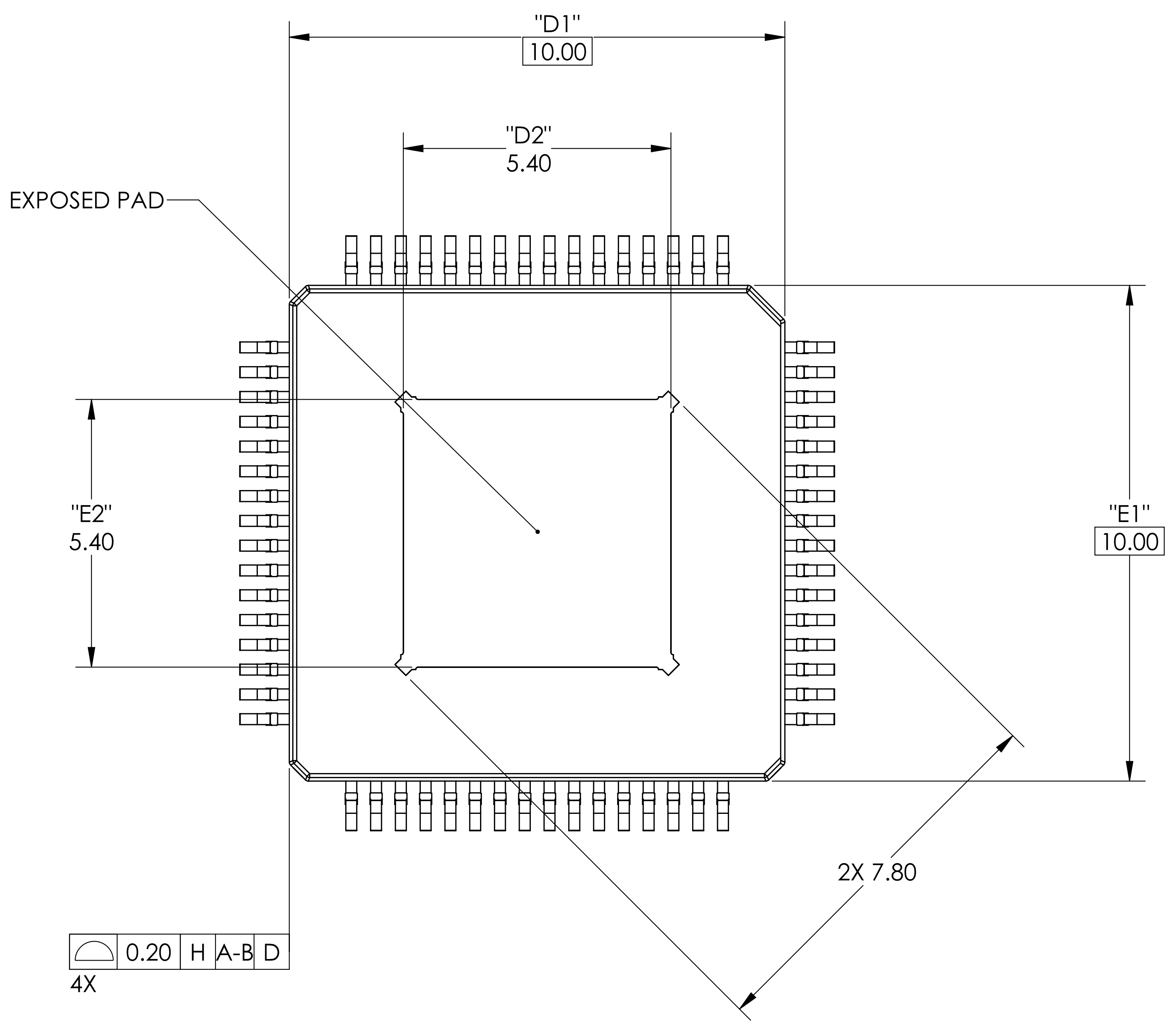
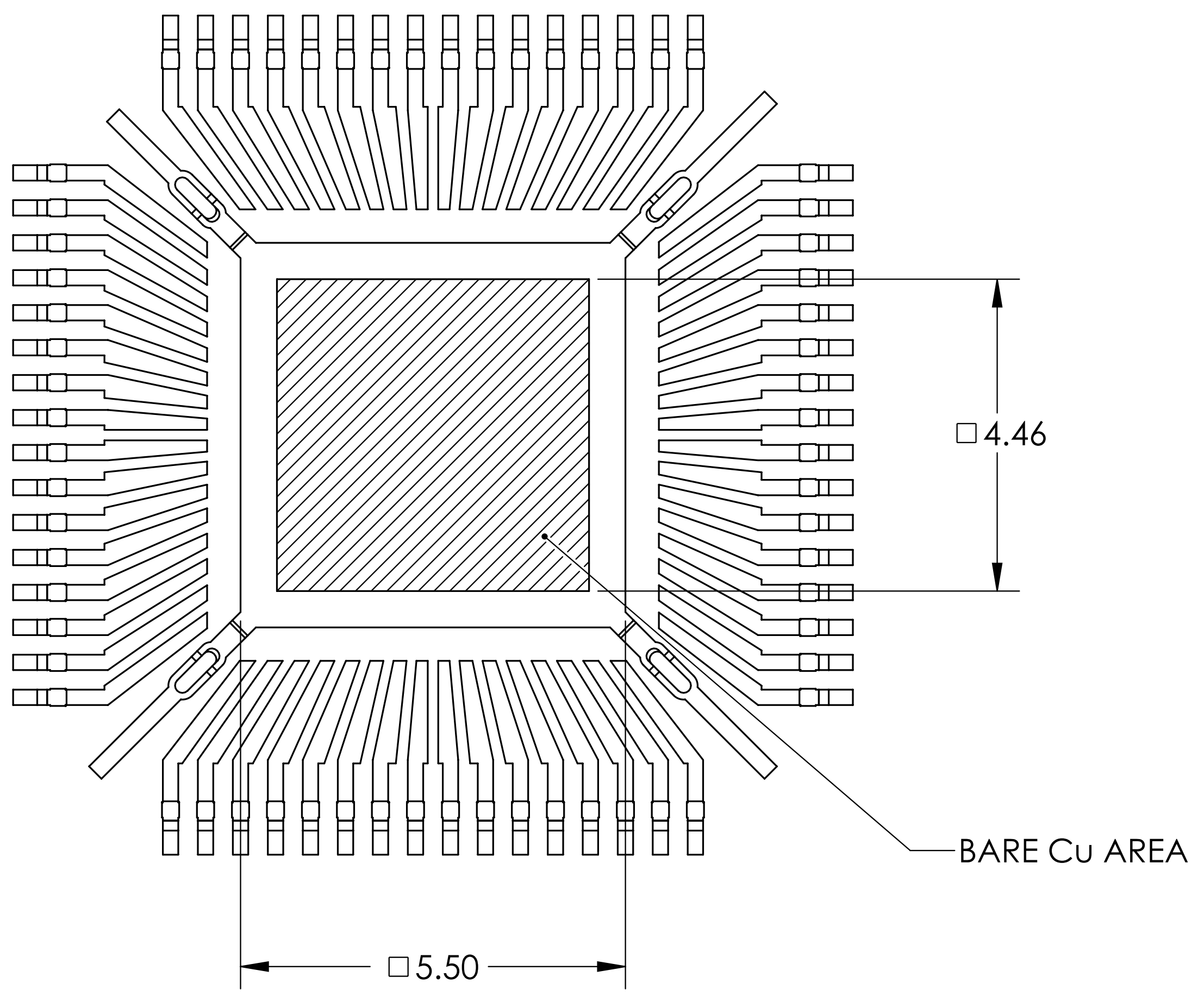
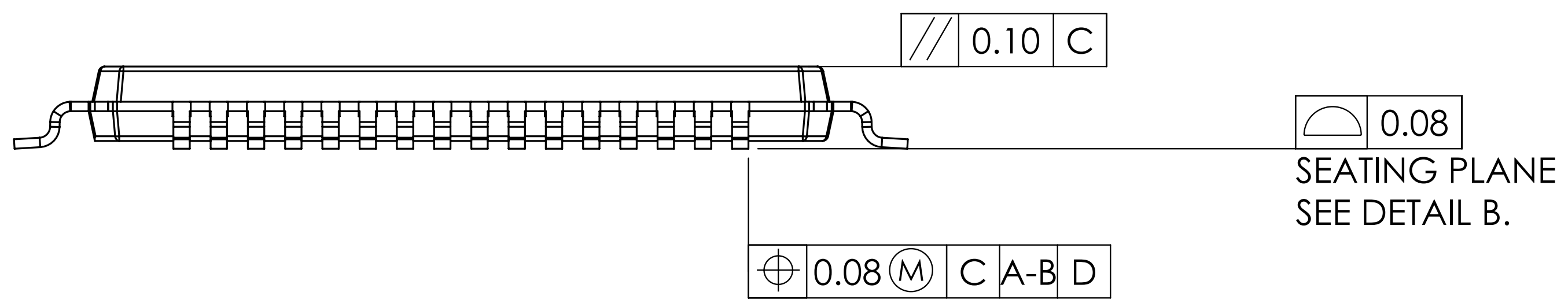
| REVISIONS | | | | | |
|---|---|---|---|---|---|
| ZONE | REV. | DESCRIPTION | DATE | APPROVED | DCN NO. |
| | A | ORGINAL RELEASE | 7/31/2020 | SS | 737 |
| | B | ADDED PLATING TOLERANCES AND ADDED DETAIL C. | 7/21/2021 | SS | 782 |

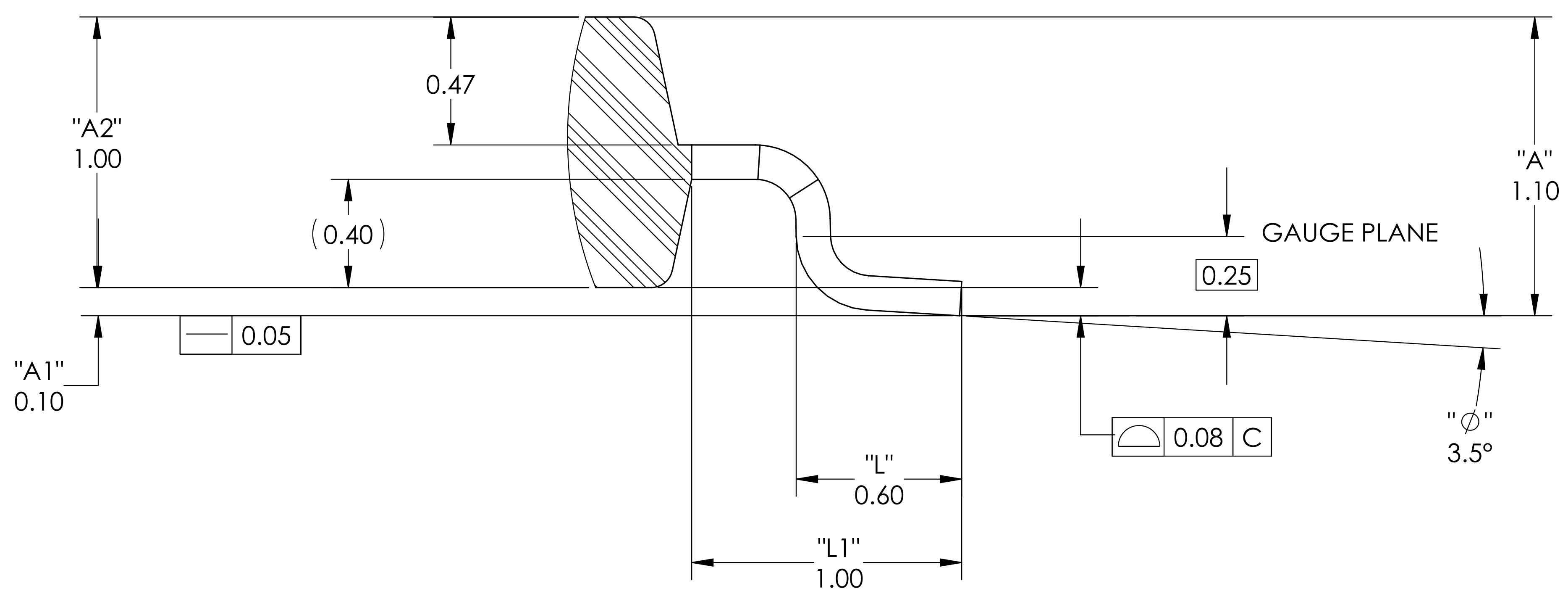




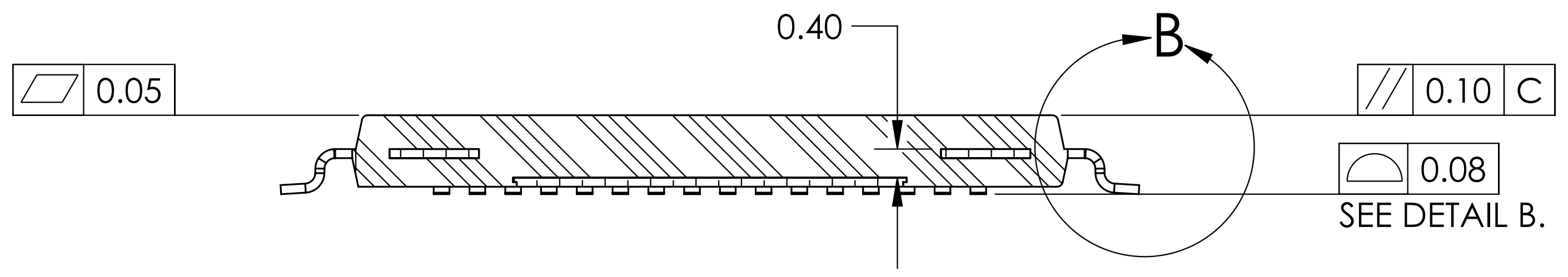








DETAIL B
SCALE 50 : 1



SECTION A-A
SCALE 10 : 1

5. DAP PLATING OPTION: GROUND RING

4. DAP SIZE: 5.50mm

3. LEAD FRAME FINISH: Ni/Pd/Au

NICKEL: 0.50µ - 2.00µ (5µin - 79µin)
PALLADIUM: 0.02µ - 0.15µ (0.79µin - 5.9µin)
GOLD: 0.003µ - 0.015µ (0.12µin - 0.59µin)

2. MATERIALS:
LEAD FRAME: EFTEC 64T 1/2 HARD WITH ADHESION ENHANCEMENT (A/E) THK = 0.127±0.008
BODY: SUMITOMO EME-G770-HD EPOXY MOLDING COMPOUND.

1. PACKAGE OUTLINE PER JEDEC, MS-026 ACD-HD.

**GENERAL NOTES: (UNLESS OTHERWISE SPECIFIED)**

| SYMBOLS | MIN. | NOM. | MAX. |
|---|---|---|---|
| A | - | - | 1.20 |
| A1 | 0.05 | - | 0.15 |
| A2 | 0.95 | 1.00 | 1.05 |
| D | 11.75 | 12.00 | 12.25 |
| D1 | 9.90 | 10.00 | 10.10 |
| D2 | 5.13 | - | 5.48 |
| E | 11.75 | 12.00 | 12.25 |
| E1 | 9.90 | 10.00 | 10.10 |
| E2 | 5.13 | - | 5.48 |
| b | 0.17 | 0.22 | 0.27 |
| c | 0.09 | - | 0.20 |
| L | .045 | 0.60 | 0.75 |
| L1 | 1.00 REF. | | |
| e | 0.50 BSC | | |
| ∅ | 0° | 3.5° | 7° |
| Y | 0.08 | | |

| NEXT ASSY | USED ON |
|---|---|
| APPLICATION | |

UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN MILLIMETERS.
ALLOWABLE TOLERANCE LIMITS ARE SHOWN IN TABLE.
THIRD ANGLE PROJECTION

MATERIAL SEE NOTE 2
FINISH SEE NOTES 3

| | NAME | DATE |
|---|---|---|
| DRAWN | S. Swen | 7/27/20 |
| CHECKED | S. Swen | 7/31/20 |
| ENG. APPR. | S. Swen | 8/4/20 |
| CUSTOMER APP. | | |

COMMENTS:

QPTECHNOLOGIES
A DIVISION OF PROMEX INDUSTRIES | QPTECHNOLOGIES.COM

TITLE:
10X10-64 TQFP eP
0.50 PITCH

SIZE D
DWG. NO. 501758
REV B
SCALE: 10:1
WEIGHT:
SHEET 1 OF 1